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July 2010

FDS6670AS

30V N-Channel PowerTrench® SyncFET™

General Description

The FDS6670AS is designed to replace a single SO-8 MOSFET and Schottky diode in synchronous DC:DC power supplies. This 30V MOSFET is designed to maximize power conversion efficiency, providing a low $R_{\text{DS(ON)}}$ and low gate charge. The FDS6670AS includes an integrated Schottky diode using Fairchild's monolithic SyncFET technology.

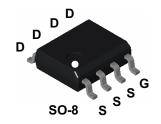
Applications

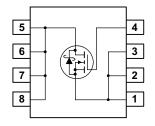
- DC/DC converter
- · Low side notebook



Features

- 13.5 A, 30 V. $R_{DS(ON)}$ max= 9.0 m Ω @ V_{GS} = 10 V $R_{DS(ON)}$ max= 11.5 m Ω @ V_{GS} = 4.5 V
- Includes SyncFET Schottky body diode
- Low gate charge (27nC typical)
- High performance trench technology for extremely low R_{DS(ON)} and fast switching
- · High power and current handling capability
- RoHS Compliant





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	13.5	Α
	- Pulsed		50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1	
T _J , T _{STG}	Operating and Storage Junction Temperat	ture Range	-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS6670AS	FDS6670AS	13"	12mm	2500 units

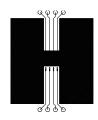
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics				II.	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 1 mA	30			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C		27		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			500	μА
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1 \text{ mA}$	1	1.7	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C		-4		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$\begin{split} &V_{GS} = 10 \text{ V}, &I_{D} = 13.5 \text{ A} \\ &V_{GS} = 4.5 \text{ V}, &I_{D} = 11.2 \text{ A} \\ &V_{GS} = 10 \text{ V}, I_{D} = 13.5 \text{A}, T_{J} = 125 ^{\circ}\text{C} \end{split}$		7.5 9 10	9 11.5 12.5	mΩ
I _{D(on)}	On–State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	50			Α
g _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 13.5 A		66		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 15 V, V _{GS} = 0 V,		1540		pF
Coss	Output Capacitance	f = 1.0 MHz		440		pF
C _{rss}	Reverse Transfer Capacitance			160		pF
R_g	Gate Resistance			2.1	4.2	Ω
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time			10	20	ns
t _r	Turn-On Rise Time	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 1 \text{ A},$		5	10	ns
$t_{d(off)}$	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		27	44	ns
t _f	Turn-Off Fall Time			18	32	ns
t _{d(on)}	Turn-On Delay Time			13	23	ns
t _r	Turn-On Rise Time	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 1 \text{ A}, \\ V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		15	27	ns
$t_{d(off)}$	Turn-Off Delay Time	$V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		24	38	ns
t _f	Turn-Off Fall Time			13	23	ns
$Q_{g(TOT)}$	Total Gate Charge at Vgs=10V			27	38	nC
Qg	Total Gate Charge at Vgs=5V	$V_{DD} = 15 \text{ V}, I_D = 13.5 \text{ A},$		16	22	nC
Q_{gs}	Gate-Source Charge			4.2		nC
Q_{gd}	Gate-Drain Charge			5.1		nC

Electrical Characteristics

T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-Sc	ource Diode Characteristics a	nd Maximum Ratings				
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 3.5 \text{ A}$ (Note 2) $V_{GS} = 0 \text{ V}, I_S = 7 \text{ A}$ (Note 2)		0.5 0.6	0.7	V
t _{rr}	Diode Reverse Recovery Time	I _F = 13.5A,		20		nS
Q _{rr}	Diode Reverse Recovery Charge	$d_{iF}/d_t = 300 \text{ A/}\mu\text{s}$ (Note 3)		15		nC

Notes: 1. R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta,IC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50°C/W when mounted on a 1 in² pad of 2 oz copper



b) 105°C/W when mounted on a .04 in² pad of 2 oz copper



c) 125°C/W when mounted on a



- Scale 1:1 on letter size paper
- **2**. Pulse Test: Pulse Width < $300\mu s$, Duty Cycle < 2.0%
- 3. See "SyncFET Schottky body diode characteristics" below.

Typical Characteristics

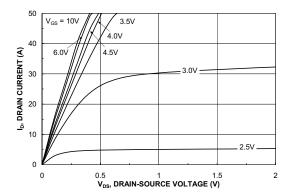


Figure 1. On-Region Characteristics.

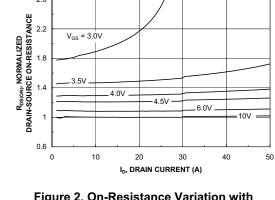


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

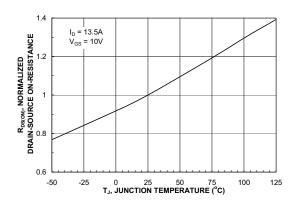


Figure 3. On-Resistance Variation with Temperature.

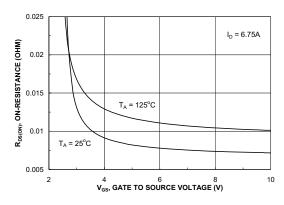


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

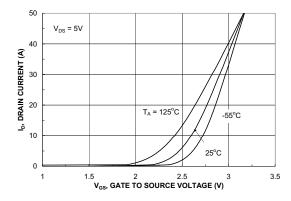


Figure 5. Transfer Characteristics.

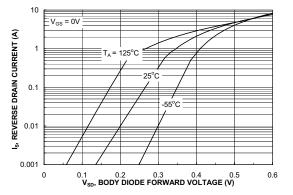


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)

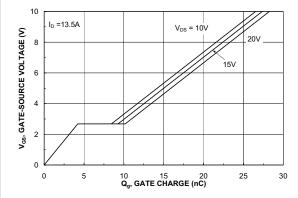
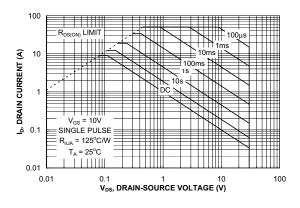


Figure 7. Gate Charge Characteristics.





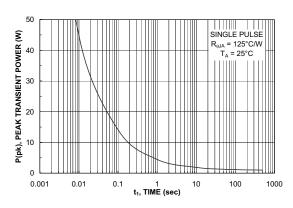


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

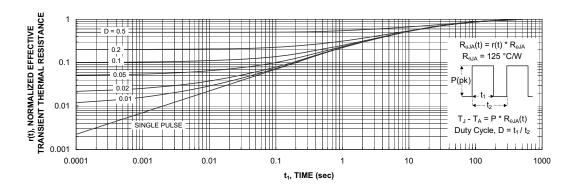


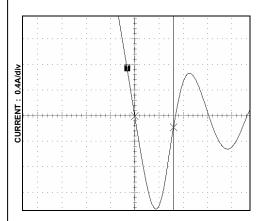
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

Typical Characteristics (continued)

SyncFET Schottky Body Diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 12 shows the reverse recovery characteristic of the FDS6670AS.



TIME: 12.5ns/div

Figure 12. FDS6670AS SyncFET body diode reverse recovery characteristic.

For comparison purposes, Figure 13 shows the reverse recovery characteristics of the body diode of an equivalent size MOSFET produced without SyncFET (FDS6670A).

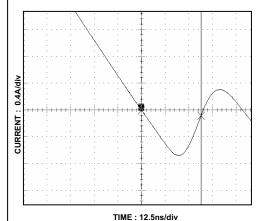


Figure 13. Non-SyncFET (FDS6670A) body diode reverse recovery characteristic.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

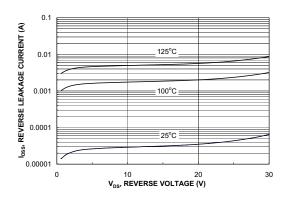


Figure 14. SyncFET body diode reverse leakage versus drain-source voltage and temperature.





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